

09/881,445

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Terms	Documents
L3 and correlation	3

**Database:**

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- IBM Technical Disclosure Bulletins

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L4 an

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result set

*DB=USPT; PLUR=YES; OP=ADJ*

<u>L4</u>	L3 and correlation	3	<u>L4</u>
<u>L3</u>	L2 and (detecting near2 signal)	89	<u>L3</u>
<u>L2</u>	L1 and (thin adj film)	5439	<u>L2</u>
<u>L1</u>	thickness near2 (reducing or reduced)	41691	<u>L1</u>

END OF SEARCH HISTORY

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L4: Entry 1 of 3

File: USPT

Oct 8, 2002

US-PAT-NO: 6462538

DOCUMENT-IDENTIFIER: US 6462538 B2

TITLE: Eddy current detection type thin film electrical resistance meter

DATE-ISSUED: October 8, 2002

## INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Harada; Yoshinori	Kashihara			JP

US-CL-CURRENT: 324/224; 324/222, 324/225, 324/230, 324/234,  
324/765, 427/8, 438/10, 438/17

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L4: Entry 2 of 3

File: USPT

Aug 7, 2001

US-PAT-NO: 6271047

DOCUMENT-IDENTIFIER: US 6271047 B1

TITLE: Layer-thickness detection methods and apparatus for wafers  
and the like, and polishing apparatus comprising same

DATE-ISSUED: August 7, 2001

## INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Ushio; Yoshijiro	Yohama			JP
Ueda; Takehiko	Tokyo			JP

US-CL-CURRENT: 438/14; 257/E21.528, 257/E21.53, 438/16, 451/41,  
451/59, 451/6, 451/8

**WEST****End of Result Set**

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L4: Entry 3 of 3

File: USPT

May 7, 1996

US-PAT-NO: 5514452

DOCUMENT-IDENTIFIER: US 5514452 A

TITLE: Magnetic multilayer film and magnetoresistance element

DATE-ISSUED: May 7, 1996

## INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Araki; Satoru	Chiba			JP
Miyauchi; Daisuke	Chiba			JP

US-CL-CURRENT: 428/213; 257/E43.005, 324/252, 360/110, 360/324,  
428/216, 428/692, 428/693, 428/694R, 428/694T, 428/694TM , 428/900

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Terms	Documents
L3 and endpoint	4

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- ☐ IBM Technical Disclosure Bulletins

**Search:**

L5

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**Set Name   Query**  
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 result set
*DB=USPT; PLUR=YES; OP=ADJ*

<u>L5</u>	L3 and endpoint	4	<u>L5</u>
<u>L4</u>	L3 and correlation	3	<u>L4</u>
<u>L3</u>	L2 and (detecting near2 signal)	89	<u>L3</u>
<u>L2</u>	L1 and (thin adj film)	5439	<u>L2</u>
<u>L1</u>	thickness near2 (reducing or reduced)	41691	<u>L1</u>

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**WEST**[Generate Collection](#)[Print](#)**Search Results - Record(s) 1 through 4 of 4 returned.**☐ 1. Document ID: US 6621264 B1

L5: Entry 1 of 4

File: USPT

Sep 16, 2003

US-PAT-NO: 6621264

DOCUMENT-IDENTIFIER: US 6621264 B1

TITLE: In-situ metalization monitoring using eddy current  
measurements during the process for removing the film

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC
Draw Desc	Image										

☐ 2. Document ID: US 6271047 B1

L5: Entry 2 of 4

File: USPT

Aug 7, 2001

US-PAT-NO: 6271047

DOCUMENT-IDENTIFIER: US 6271047 B1

TITLE: Layer-thickness detection methods and apparatus for wafers  
and the like, and polishing apparatus comprising same

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	Claims	KWIC
Draw Desc	Image										

☐ 3. Document ID: US 5949927 A

L5: Entry 3 of 4

File: USPT

Sep 7, 1999

US-PAT-NO: 5949927

DOCUMENT-IDENTIFIER: US 5949927 A

TITLE: In-situ real-time monitoring technique and apparatus for  
endpoint detection of thin films during chemical/mechanical  
polishing planarization

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments	KWIC
Draw Desc	Image									

☐ 4. Document ID: US 5433651 A

L5: Entry 4 of 4

File: USPT

Jul 18, 1995

US-PAT-NO: 5433651

DOCUMENT-IDENTIFIER: US 5433651 A

TITLE: In-situ endpoint detection and process monitoring method and apparatus for chemical-mechanical polishing

Full	Title	Citation	Front	Review	Classification	Date	Reference	Sequences	Attachments
Draw Desc	Image								

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Terms	Documents
L3 and endpoint	4

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